

In re Patent Application of  
**MAGNI ET AL.**  
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positioning a mold adjacent the integrated circuit, the mold comprising a half-mold having an insert projecting towards the inside of the mold, the insert being elastically deformable and abutting in pressing contact against at least one portion of the integrated circuit; and

injecting a resin into the mold so that the protective package has a hole aligned with the at least one portion of the integrated circuit.

9. A method according to Claim 8, further comprising supplying pressure to the insert.

10. A method according to Claim 9, wherein the pressure is supplied to a back face of the insert opposite the integrated circuit.

11. A method according to Claim 9, wherein the half-mold has an opening therein for connection to a pressure source.

12. A method according to Claim 8, wherein the at least one portion comprises a border portion of the integrated circuit.

13. A method according to Claim 8, wherein the insert comprises a cylindrical skirt connected to adjacent portions of the half-mold, and an end carried by the cylindrical skirt.

14. A method for forming a plastic protective package for an integrated circuit, the method comprising:

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positioning a mold adjacent the integrated circuit, the mold comprising a half-mold having an elastically deformable membrane projecting towards the inside of the mold;

supplying pressure to urge the elastically deformable membrane into pressing contact against at least one portion of the integrated circuit; and

injecting a resin into the mold so that the protective package has a hole aligned with the at least one portion of the integrated circuit.

15. A method according to Claim 14, wherein the pressure is supplied to a back face of the insert opposite the integrated circuit.

16. A method according to Claim 14, wherein the half-mold has an opening therein for connection to a pressure source.

17. A method according to Claim 14, wherein the at least one portion comprises a border portion of the integrated circuit.

18. A method according to Claim 14, wherein the elastically deformable membrane comprises a cylindrical skirt connected to adjacent portions of the half-mold, and an end carried by the cylindrical skirt.

19. A mold for molding a plastic protective package for encapsulating an integrated circuit that can be at least partially activated from outside of the protective package, the mold comprising:

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first and second half-molds which are laid onto each other to form a space for containing the integrated circuit; and

an elastically deformable insert connected to the first half-mold and projecting substantially towards the integrated circuit to abut in pressing contact against at least one portion of the integrated circuit during a molding phase.

20. A mold according to Claim 19, wherein the first half-mold has an opening therein for connection to a pressure source.

21. A mold according to Claim 19, wherein the at least one portion comprises a border portion of the integrated circuit.

22. A mold according to Claim 19, wherein the insert comprises a cylindrical skirt connected to adjacent portions of the first half-mold, and an end carried by the cylindrical skirt.

23. A mold for molding a plastic protective package for encapsulating an integrated circuit that can be at least partially activated from outside of the protective package, the mold comprising:

first and second half-molds comprising metal and which are laid onto each other to form a space for containing the integrated circuit; and

an elastically deformable membrane connected to the first half-mold and projecting substantially towards the